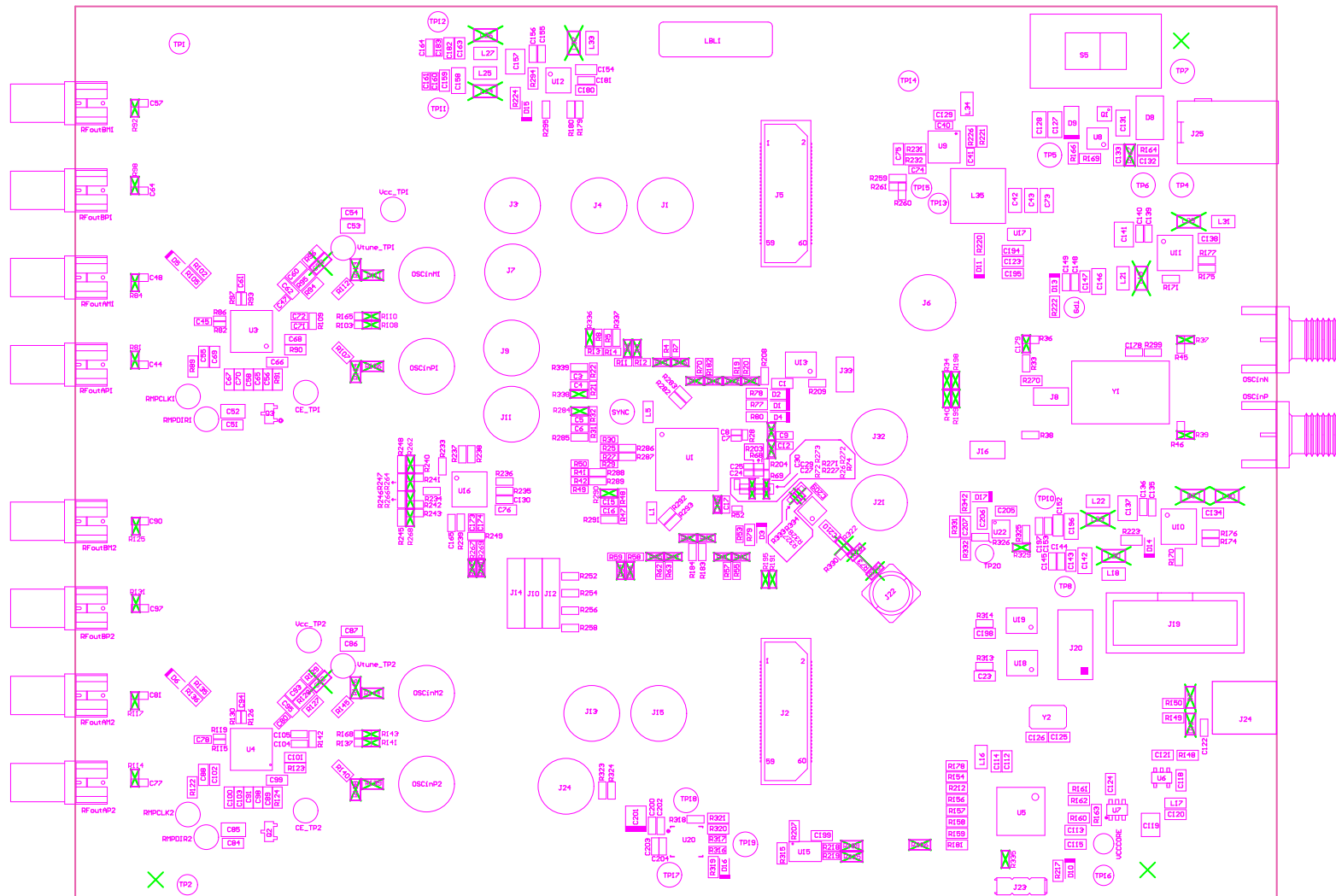


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

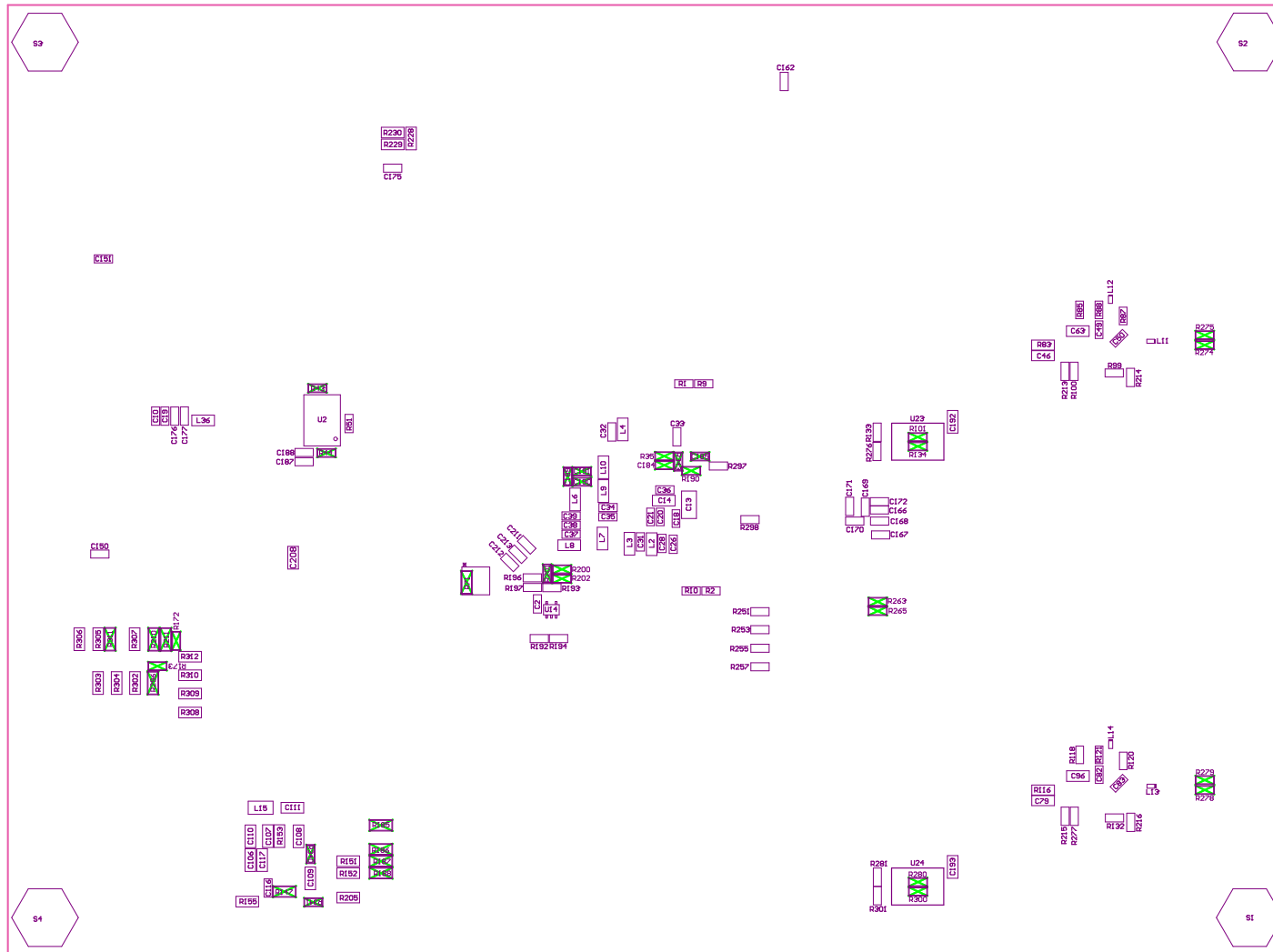


COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

001

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDA-01021	REV:	E2	SUN REV:
IGNORE ->	ASSEMBLY TOP	TID #:	01021		
PLOT NAME =	Top Assembly Drawing	GENERATED :	10/13/2017	5:02:16 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #:	TIDA-01021	REV:	E2	SUN REV:
LAYER NAME =	ASSEMBLY BOTTOM				
TID #:	01021				
PLOT NAME =	Bottom Assembly Drawing		GENERATED	10/13/2017	5:03:20 PM
					TEXAS INSTRUMENTS

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